

Device Selection Guide

Code	Chip Materials	Emitted Color	Resin Color
R6	AlGaInP	Brilliant Red	
GH	InGaN	Brilliant Green	- Water Clear
ВН	InGaN	Blue	-

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Code	Rating	Unit	
Reverse Voltage	V _R		5	V	
		R6	25	mA	
Forward Current	I _F	GH	25		
		ВН	20		
		R6	60		
Peak Forward Current	I _{FP}	GH	100	mA	
(Duty 1/10 @1KHz)		ВН	100		
		R6	60		
Power Dissipation	Pd	GH	95	mW	
		ВН	75		
		R6	2000		
Electrostatic	ESD	GH	150	V	
Discharge(HBM)		ВН	150		
Operating Temperature	T _{opr}		-40 ~ +85	$^{\circ}$	
Storage Temperature	Tstg		-40 ~ +90	$^{\circ}$	
Soldering Temperature	Tsol			: 260 $^{\circ}{\mathbb{C}}$ for 10 sec.	
			Hand Soldering : 350 $^{\circ}{\mathbb{C}}$ for 3 sec.		



Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Code	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	R6	72.0		180	_	
		GH	112		285	mcd _	
		ВН	45.0		112		
Viewing Angle	2θ _{1/2}			100		Deg	_
		R6		632		_	
Peak Wavelength	λр	GH		518		nm	
		ВН		468			
	λd	R6		624		_	I _F =20mA
Dominant Wavelength		GH		525		nm	I _F =2UIIIA
·		ВН		470			
	Δλ	R6		20		- nm	
Spectrum Radiation Bandwidth		GH		35			
		ВН		25			
Forward Voltage	V_{F}	R6	1.7		2.4	_	
		GH	2.7		3.7	V -	
		ВН	2.7		3.7		
Reverse Current	I _R	R6			10		V _R =5V
		GH			50	μΑ	
		ВН			50		

Note:

^{1.}Tolerance of Luminous Intensity: ±11%

^{2.}Tolerance of Forward Voltage: ±0.1V



R6

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
Q1	72.0	90.0		
Q2	90.0	112		L 00 × A
R1	112	140	mcd	I _F =20mA
R2	140	180		

GH

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
R1	112	140		
R2	140	180		
S1	180	225	mcd	I _F =20mA
S2	225	285		

BH

Bin Range of Luminous Intensity

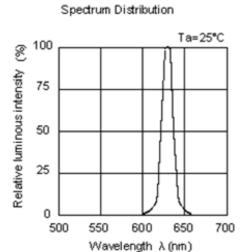
Bin Code	Min.	Max.	Unit	Condition
P1	45.0	57.0		
P2	57.0	72.0		
Q1	72.0	90.0	mcd	I _F =20mA
Q2	90.0	112		

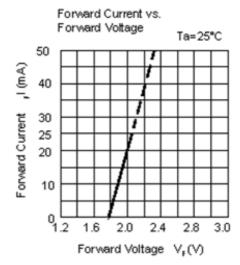
Note:

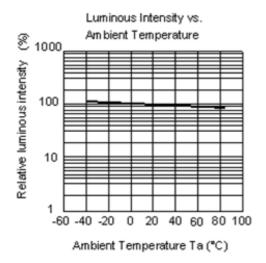
Tolerance of Luminous Intensity: ±11%

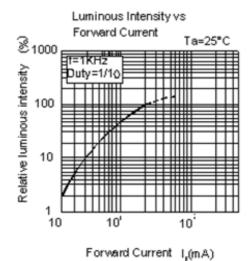


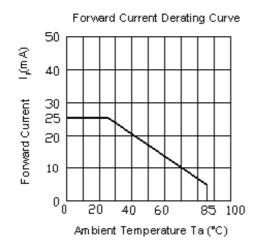
Typical Electro-Optical Characteristics Curves R6

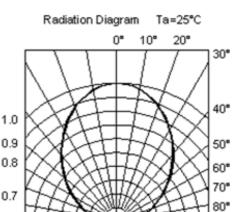












0.5

0.3

0.1

0.2

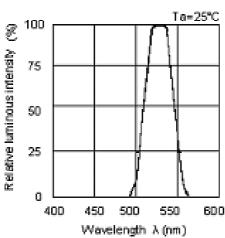
0.4

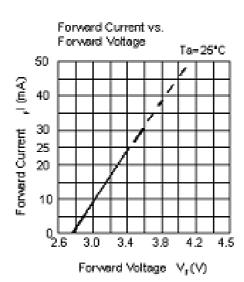
90°

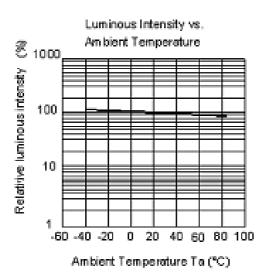


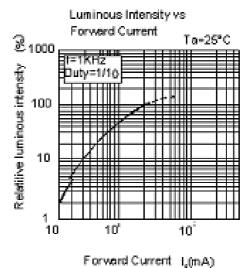
Typical Electro-Optical Characteristics Curves GH

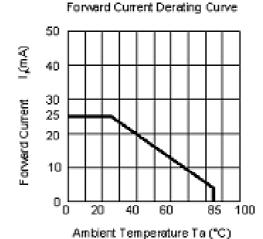


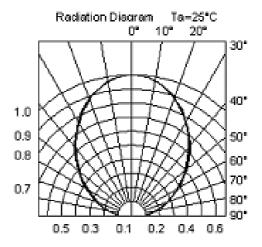






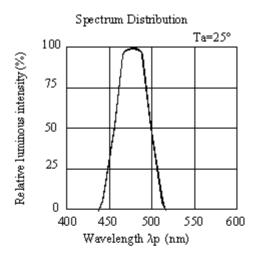


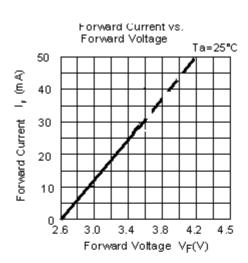


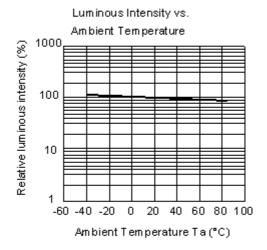


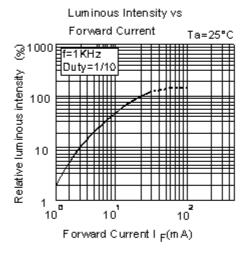


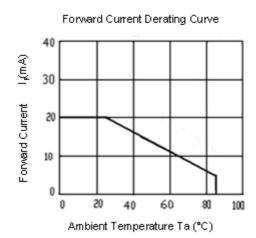
Typical Electro-Optical Characteristics Curves BH

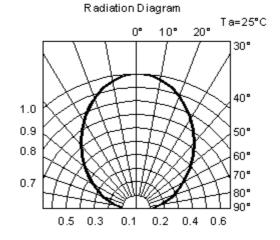






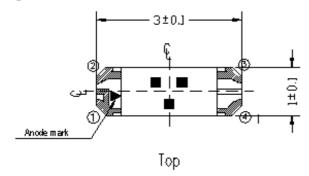


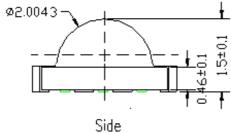


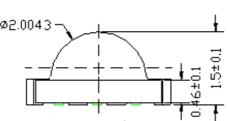


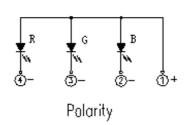


Package Dimension

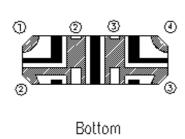


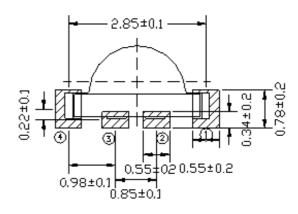






Recommend Sodering Pad



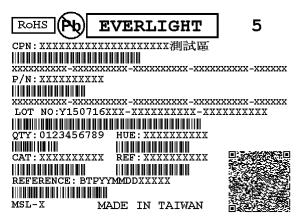


Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned ±0.1mm. Unit = mm



Moisture Resistant Packing Materials Label Explanation



• CPN: Customer's Product Number

P/N: Product NumberQTY: Packing Quantity

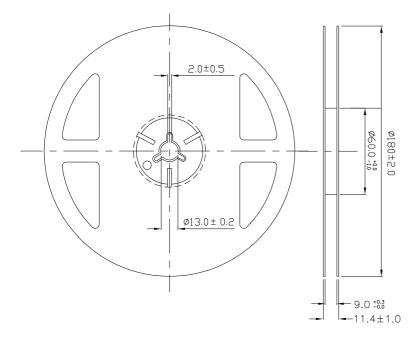
· CAT: Luminous Intensity Rank

· HUE: Chromaticity Coordinates & Dom. Wavelength Rank

• REF: Forward Voltage Rank

· LOT No: Lot Number

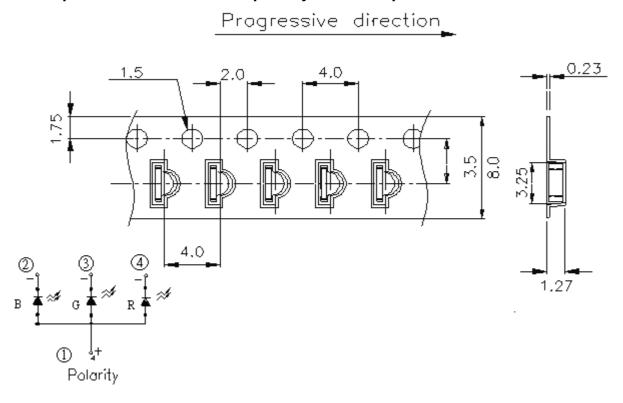
Reel Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

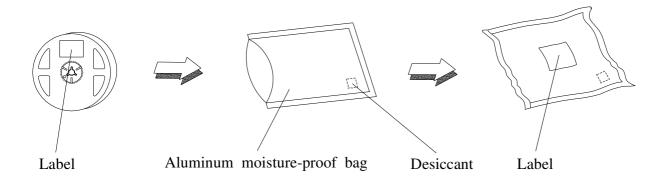


Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Moisture Resistant Packaging





Precautions For Use

1. Over-current-proof

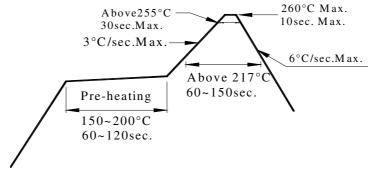
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30℃ or less and 60% RH or less.

If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for 24 hours.

- 3. Soldering Condition
- 3.1 Pb-free solder temperature profile



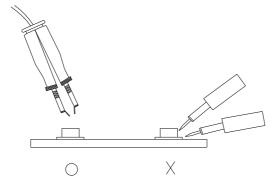
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



DATASHEET SMD • B 12-23C/R6GHBHC-A30/2C



Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.